

Title (en)  
Method of and apparatus for making stencil

Title (de)  
Vorrichtung und Verfahren zum Herstellen von Schablonen

Title (fr)  
Méthode et appareil de fabrication de stencil

Publication  
**EP 1080926 A3 20010620 (EN)**

Application  
**EP 00118788 A 20000830**

Priority  
• JP 24583999 A 19990831  
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• JP 24623099 A 19990831

Abstract (en)  
[origin: EP1080926A2] A stencil is made by the use of a thermal head which has an array of resistance heater element arranged in a main scanning direction. The resistance heater elements are selectively driven while the stencil material is conveyed in a sub-scanning direction intersecting the main scanning direction so that perforations are formed in the stencil material in a predetermined size at a first pitch in the main scanning direction and a second pitch in the sub-scanning direction. The stencil material is perforated so that unperforated portions which continuously extend in one of the main scanning direction and the sub-scanning direction to separate perforations in the other of the main scanning direction and the sub-scanning direction are left in the stencil material. <IMAGE>

IPC 1-7  
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IPC 8 full level  
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CPC (source: EP)  
**B41C 1/144** (2013.01); **B41J 2/355** (2013.01); **B41C 1/14** (2013.01); **B41J 2202/32** (2013.01)

Citation (search report)  
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• [A] PATENT ABSTRACTS OF JAPAN vol. 1997, no. 03 31 March 1997 (1997-03-31)

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